

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"5834848".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:30
L2	41	"5834848".URPN.	USPAT	OR	ON	2006/02/03 20:30
L3	1431	semiconductor with module with (capacitor or resistor)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:30
L4	497	semiconductor with module with (capacitor or resistor)	USPAT	OR	ON	2006/02/03 20:30
L5	24	("4672152" "4777092" "4821142" "5024975" "5206190" "5212121" "5242867" "5283210" "5342674" "RE34887" "5578533" "5710082" "5766741" "5821181" "5825632" "5968858" "5998314" "6118649" "6118671" "6228196" "6241838" "6265090" "6270880" "6316374").PN.	USPAT	OR	ON	2006/02/03 20:30
L6	6	("5153709" "5414300" "5473512" "5477009" "5639989" "5818699").PN.	USPAT	OR	ON	2006/02/03 20:30
L7	25	"5818699".URPN.	USPAT	OR	ON	2006/02/03 20:30
L8	1	"5818699".pn.	USPAT	OR	ON	2006/02/03 20:30
L9	210	Ball with grid with array with typically with solder	USPAT	OR	ON	2006/02/03 20:30
L10	29	"257"/\$.ccls. and substrate with second adj surface with density	USPAT	OR	ON	2006/02/03 20:30
L11	0	"5795799pn."	USPAT	OR	ON	2006/02/03 20:30
L12	1	"5795799".pn.	USPAT	OR	ON	2006/02/03 20:30
L13	560	"257"/\$.ccls. and resin with encapsu\$9 with prot\$9	USPAT	OR	ON	2006/02/03 20:30
L14	188	("257"/\$.ccls. and resin with encapsu\$9 with prot\$9) and (heat moisture enviroment) with prot\$9	USPAT	OR	ON	2006/02/03 20:30
L15	0	(257/779257/738257/772257/78025 7/782257/783).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/03 20:30
L16	1121	(257/779).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/03 20:30

L17	1845	(257/738).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/03 20:30
L18	532	(257/772).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/03 20:30
L19	1396	(257/780).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/03 20:30
L20	800	(257/782).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/03 20:30
L21	1088	(257/783).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/03 20:30
L22	5083	((257/779).CCLS.) ((257/738). CCLS.) ((257/772).CCLS.) ((257/780).CCLS.) ((257/782). CCLS.) ((257/783).CCLS.)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:30
L23	0	JP-200023831-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:30
L24	128	(copper cu) with ball with (tin Sn) with pad	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:52
L25	2279	(copper cu) with (powder ball) with (tin Sn) and (semiconductor IC chip integrated adj circuit die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:30
L26	746	((copper cu) with (powder ball) with (tin Sn) and (semiconductor IC chip integrated adj circuit die)) and (copper cu) with (powder ball) with (tin Sn) same (solder bump junction connection)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:30

L27	183	bump with plastic with (powder particles grain ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:30
L28	1045	solder with plastic with (powder particles grain ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:30
L29	2	"20020171157".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:30
L30	2	JP-2000246483-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:30
L31	1	2000-657021.NRAN.	DERWENT	OR	OFF	2006/02/03 20:30
L32	1	2000-657021.NRAN.	DERWENT	OR	OFF	2006/02/03 20:30
L33	2	JP-2000223831-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:30
L34	1	2000-555536.NRAN.	DERWENT	OR	OFF	2006/02/03 20:30
L35	2	JP-07235565-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:30
L36	2	"6340113".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:30
L37	23	("4737112" "4740252" "5118029" "5156321" "5248475" "5269453" "5296649" "5299730" "5317191" "5328522" "5385290" "5427865" "5429293" "5540379" "5573602" "5573859" "5591941" "5801446" "5834824" "5885849" "5950908" "6056831" "6077380").PN.	USPAT	OR	ON	2006/02/03 20:30
L38	2	"6235996".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:30

L39	103	(copper cu) with ball with (tin Sn) with bump	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:30
L40	384	((copper cu) with (powder ball) with (tin Sn) and (semiconductor IC chip integrated adj circuit die)) and (copper cu) with (powder ball) with (tin Sn) same (solder bump junction connection)	USPAT	OR	ON	2006/02/03 20:30
L41	14	"6207259".URPN.	USPAT	OR	ON	2006/02/03 20:30
L42	4	("4398975" "4435611" "5117069" "5346750").PN.	USPAT	OR	ON	2006/02/03 20:30
L43	6	kazuko.in. and solder	USPAT	OR	ON	2006/02/03 20:30
L44	25	bump with plastic adj ball	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:30
L45	158	(bump with plastic with (powder particles grain ball)) not (bump with plastic adj ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:30
L46	2237646	(257/779 257/738 257/772 257/780 257/782 257/783).ccls. "257" "779000" "257" "738000" "257" "772000" "257" "780000" "257" "782000" "257" "783000" Y	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:30
L47	2	"5834848".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:30
L48	3	"5","818","699".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:30
L49	30770	(IC integrated adj circuit semiconductor chip die wafer) and (pad connectors land) and (substrate base PCB board printed near1 circuit) and ((copper cu) (tin Sn))	US-PGPUB	OR	ON	2006/02/03 20:53
L50	12846	(IC integrated adj circuit semiconductor chip die wafer) and (pad connector land) and (substrate base PCB board printed near1 circuit) and ((copper cu) (tin Sn)) and alloy	US-PGPUB	OR	ON	2006/02/03 20:53

L51	572	((IC integrated adj circuit semiconductor chip die wafer) and (pad connector land) and (substrate base PCB board printed near1 circuit) and ((copper cu) (tin Sn)) and alloy).clm.	US-PGPUB	OR	ON	2006/02/03 20:54
L52	76	((IC integrated adj circuit semiconductor chip die wafer) and (pad connector land) and (substrate base PCB board printed near1 circuit) and melting and ((copper cu) (tin Sn)) and alloy).clm.	US-PGPUB	OR	ON	2006/02/03 20:54